



PRODUCT/PROCESS CHANGE NOTIFICATION

PCN MMS-MIC/11/6485
Notification Date 06/20/2011

STM8S20x improvement

Table 1. Change Implementation Schedule

Forecasted implementation date for change	01-Oct-2011
Forecasted availability date of samples for customer	01-Sep-2011
Forecasted date for STMicroelectronics change Qualification Plan results availability	01-Oct-2011
Estimated date of changed product first shipment	01-Oct-2011

Table 2. Change Identification

Product Identification (Product Family/Commercial Product)	STM8S20x family
Type of change	Product design change
Reason for change	Yield and manufacturing capability improvement to secure the production
Description of the change	Design improvement that is affecting the upper connection layers is implemented in order to improve the yield and manufacturing capability. The functionality and the parametric figures remain unchanged. The implementation is software and hardware compatible with the previous revisions.
Product Line(s) and/or Part Number(s)	See attached
Description of the Qualification Plan	See attached
Change Product Identification	See attached description at page 5
Manufacturing Location(s)	

DOCUMENT APPROVAL

Name	Function
Colonna, Daniel	Division Marketing Manager
Buffa, Michel	Division Product Manager
Narche, Pascal	Division Q.A. Manager

How can the change be seen?

Traceability of the change is ensured by ST internal tools.

New Finish good identification is printed on the labels.

The new revision letter is changed as follows:

- For Rousset plant, X or Y to W
- For Global Foundry plant, 6 to 7

Sample ordering process

The following process should be followed when ordering samples:

1. Wait until the forecasted availability date for samples for customer in table 1 has passed.
2. Enter a NON STANDARD samples order with a note indicating the PCN reference 'MMS-MIC/11/6485'. This is important in order to ensure that samples are manually scheduled with the correct product revision.

List of the involved Sales Types for the PCN MMS-MIC/11/6485

Involved Commercial Products		
STM8S207C6T6	STM8S207M8T6B	STM8S207S6T6CTR
STM8S207C6T6TR	STM8S207MBT6B	STM8S207S8T3C
STM8S207C8T3	STM8S207R6T6	STM8S207S8T3CTR
STM8S207C8T6	STM8S207R8T3	STM8S207S8T6C
STM8S207C8T6TR	STM8S207R8T3TR	STM8S207S8T6CTR
STM8S207CBT3	STM8S207R8T6	STM8S207SBT6C
STM8S207CBT6	STM8S207R8T6C	STM8S208C6T3
STM8S207CBT6TR	STM8S207R8T6TR	STM8S208C8T6
STM8S207K6T3C	STM8S207RBT6	STM8S208CBT6
STM8S207K6T3CTR	STM8S207RBT6C	STM8S208MBT6B
STM8S207K6T6C	STM8S207RBT6TR	STM8S208R8T6
STM8S207K6T6CTR	STM8S207S6T3C	STM8S208RBT6
STM8S207K8T6C	STM8S207S6T3CTR	STM8S208S6T3C
STM8S207K8T6CTR	STM8S207S6T6C	STM8S208S6T6C

MMS MCD Qualification Plan

RERMCD1111

STM8S105 revX (RS8F) or rev7 (CH6F)

STM8S20x revW (RS8F) or rev7 (CH6F)

CMOSF9 RS8F & CH6F

Product / Process information	
Commercial product	STM8S105xxxxx STM8S20xxxxxx
Product line	766X19 765X19
Product description	STM8S105 STM8S20x
Finish Good Code	8S105xxxx\$xx 8S20xxxxx\$xx
Production Mask Set revision	F766XXXX & F766XXX7 F765XXXW & F765XXX7
Product Division	Microcontrollers Division (MCD)
Silicon process technology	CMOSF9 GO1
Wafer fabrication location	RS8F – ST Rousset 8", France CH6F – Global Foundry - Singapor
Electrical Wafer Sort test plant location	RS8F – ST Rousset 8", France Ang Mo Kio EWS, Singapor

1.1 Objectives

The aim of this document is to present the qualification plan to assess the new mask revisions of the STM8S105 & STM8S20x.

1.2 Reliability Plan

Short description						
<i>Descript.</i>	<i>Test/Method</i>	<i>Conditions</i>	<i>Sample Size</i>	<i>Criteria</i>	<i>Read out /Duration</i>	<i>Lot 1</i>
<i>Electrostatic discharge - Human Body Model</i>						
ESD HBM	0060102 JESD22-A114	LQFP48	3 x 1 [3 x 1]	2KV [4KV]	2KV [4KV]	
<i>Electrostatic discharge - Charge Device Model</i>						
ESD CDM	0060102 JESD22-C101	LQFP48	3 x 1	1000V class III	1000V	
<i>LATCH UP</i>						
LU	0018695 JESD78	LQFP48	6 x 1	A0/R1	125°C	
<i>NVM Endurance & Data Retention - 10K program / 300k data EW @ 125°C then Storage</i>						
EDR	JESD22-A117 JESD22-A103	HTSL 150°C	80 x 1	A0/R1 10K/300K + 168h	168h	
<i>High Temperature Operating Live</i>						
HTOL	MIL-STD-883 Method 1005 JESD22-A108	140°C , 5v5	80 x 1	A0/R1 500h	500h	

[...] Monitoring

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